L Number Hits Search Text DB 50 143 (individual\$3 with (shutter shield) with (coat\$3 deposit\$3)) 51 60 ((individual\$3 with (shutter shield)) same (coat\$3 deposit\$3)) Coat\$3 deposit\$3)) DERWEN	·
(coat\$3 deposit\$3)) 51 60 ((individual\$3 with (shutter shield)) same EPO;	· I
51 60 ((individual\$3 with (shutter shield)) same EPO;	PUB I
	NT
52 457 ((118/720) or (118/721)).CCLS. USPAT	; 2003/06/27 13:51
US-PGI	PUB
53 5 (((118/720) or (118/721)).CCLS.) and USPAT	; 2003/06/27 13:53
((individual each) with (shutter shield)) US-PGI	
54 53 (156/345.3).CCLS. USPAT	; 2003/06/27 13:54
US-PGI	
55 69 (118/\$.CCLS.) and ((shield shutter) with USPAT	; 2003/06/27 14:13
(individual)) US-PGI	
56 607 (118/504).CCLS. USPAT.	; 2003/06/27 14:13
US-PGI	
- 453 ((118/720) or (118/721)).CCLS. USPAT	; 2003/06/27 13:51
US-PGI	
- 0 (((118/720) or (118/721)).CCLS.) and USPAT	; 2003/03/21 09:41
(laser with shutter with individual) US-PG	
- 2 (((118/720) or (118/721)).CCLS.) and USPAT	•
(laser with shutter) US-PG	
- 1 ("5980975").PN. USPAT	
US-PG	
- 11 (((118/720) or (118/721)).CCLS.) and USPAT	· I
(shutter with (individual multipl\$5 US-PG	PUB
plural\$5))	
- 104 (118/\$.CCLS.) and (shutter with USPAT	
(individual multipl\$5 plural\$5)) US-PG	
- 27 ("2432950" "2571167" "2765765" USPAT	2003/03/21 12:48
"2906235" "2978364" "3063867"	
"3117025" "3352282" "3371138"	
"3502051" "3504325" "3549414"	
"3573672" "3600675" "3670693"	
"3756851" "3773541" "3866155"	
"3963982" "3992760" "4093914"	
"4107349" "4122147" "4323031"	
"4343827" "4378382" "4391034").PN.	2003/03/21 13:04
- 8 ("3853740" "4051010" "4410407" USPAT	2003/03/21 13:04
"4894132" "5076205" "5241152"	
	: 2003/03/21 13:22
- 460 shutter with (individual multipl\$5 USPAT plural\$5) with (substrate wafer US-PG	
plural\$5) with (substrace water 05-rg.	
- 413 (shutter with (individual multipl\$5 USPAT	; 2003/03/21 13:19
plural\$5) with (substrate wafer US-PG	•
semiconsuctor laser)) not ((118/\$.CCLS.)	
and (shutter with (individual multipl\$5	
plural\$5)))	
- 277 (shutter with (individual multipl\$5 USPAT	; 2003/03/21 13:25
plural\$5) with (substrate wafer US-PG	
semiconductor)) and (deposit\$3 coat\$3	
(form\$3 with film))	
- 277 (shutter with (individual multipl\$5 USPAT	; 2003/06/27 12:56
plural\$5 each) with (substrate wafer US-PG	PUB
semiconductor)) and (deposit\$3 coat\$3	
(form\$3 with film))	
- 91 (shutter with (individual multipl\$5 EPO;	JPO; 2003/03/21 13:28
plural\$5 each) with (substrate wafer DERWE	NT
semiconductor)) and (deposit\$3 coat\$3	
(form\$3 with film))	